

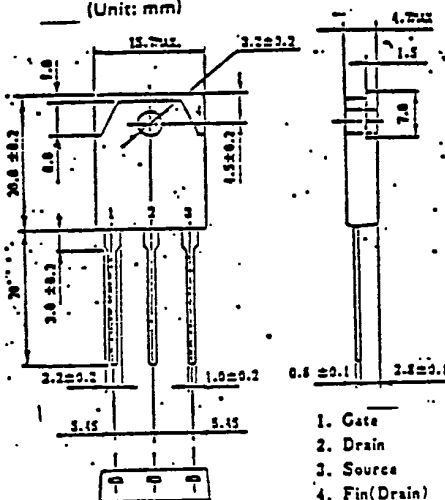


MOS FIELD EFFECT TRANSISTOR

2SK825

**FAST SWITCHING
N-CHANNEL SILICON POWER MOS FET**

PACKAGE DIMENSIONS
(Unit: mm)



Features

Suitable for switching power supplies,
actuator controls and pulse circuits
Low $R_{DS(on)}$

Absolute Maximum Ratings ($T_a = 25^\circ\text{C}$)

Drain to Source Voltage	V_{DS}	450V
Gate to Source Voltage	V_{GS}	$\pm 20V$
Continuous Drain Current	$I_D(DC)$	$\pm 15A$
Pulse Drain Current	$I_D(pulse)$	$* \pm 40A$
Total Power Dissipation	P_T	3.0W
Total Power Dissipation	P_{T*}	120W
Channel Temperature	T_{ch}	150 $^\circ\text{C}$
Storage Temperature	T_{stg}	-55 to +150 $^\circ\text{C}$

* $PW \leq 300 \mu s$, Duty Cycle $\leq 2\%$

** $T_c = 25^\circ\text{C}$

Electrical Characteristics ($T_a = 25^\circ\text{C}$)

Characteristics	Symbol	Min.	Typ.	Max.	Unit	Test Conditions
Drain Leakage Current	I_{DSS}			100	μA	$V_{DS} = 150V, V_{GS} = 0$
Gate to Source Leakage Current	I_{GSS}			± 100	nA	$V_{GS} = \pm 20V, V_{DS} = 0$
Gate to Source Cutoff Voltage	$V_{GS(off)}$	1.5		3.5	V	$V_{DS} = 10V, I_D = 1.0mA$
Forward Transfer Admittance	y_{fs}	5.0			S	$V_{DS} = 10V, I_D = 7.5A$
Drain to Source On-State Resistance	$R_{DS(on)}$		0.4	0.5	Ω	$V_{GS} = 10V, I_D = 7.5A$
Input Capacitance	C_{iss}		2000		pF	$V_{DS} = 10V,$ $V_{GS} = 0,$
Output Capacitance	C_{oss}		500		pF	$f = 1.0MHz$
Reverse Transfer Capacitance	C_{rss}		140		pF	$I_D = 7.5A$
Turn-On Delay Time	$t_d(on)$		20		ns	$V_{GS(on)} = 10V,$
Rise Time	t_r		35		ns	$V_{CC} = 150V,$
Turn-Off Delay Time	$t_d(off)$		100		ns	$R_L = 20 \Omega$
Fall Time	t_f		35		ns	

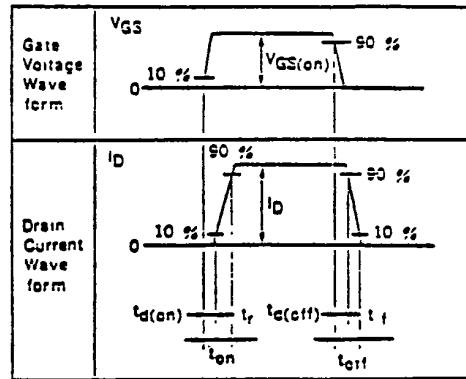
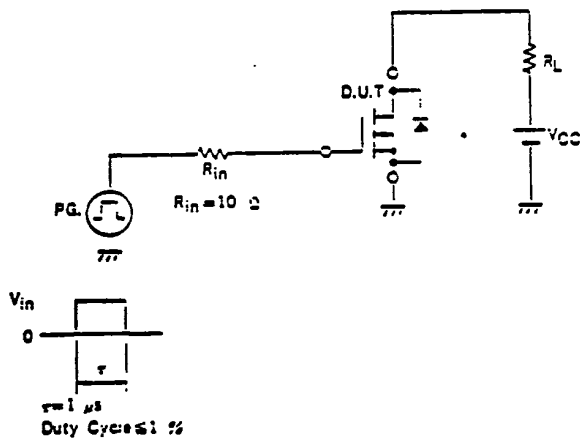
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TURN-ON AND TURN-OFF TIME TEST CIRCUIT

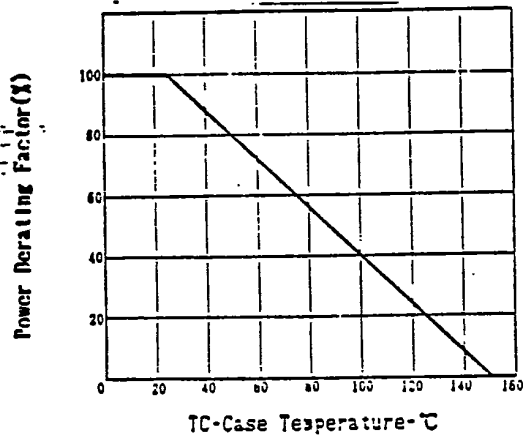
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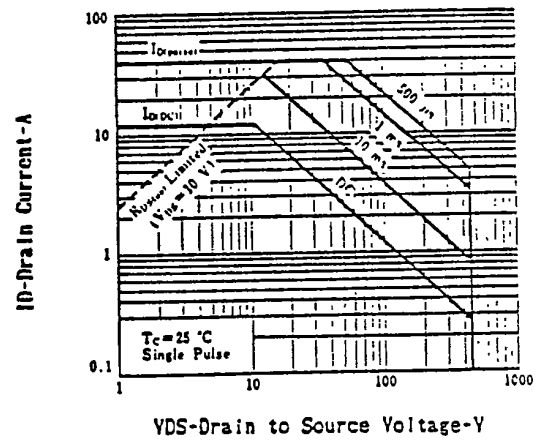
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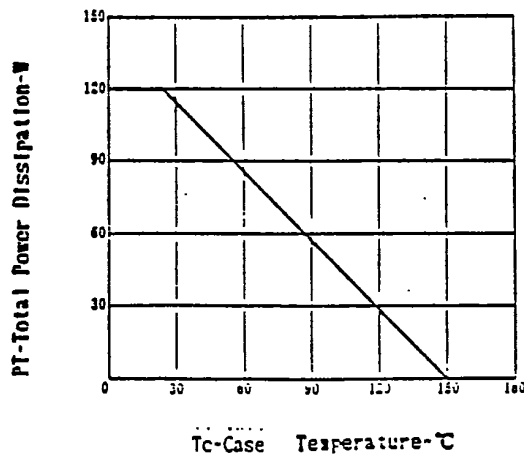
DERATING FACTOR OF FORWARD BIAS SAFE OPERATING AREA



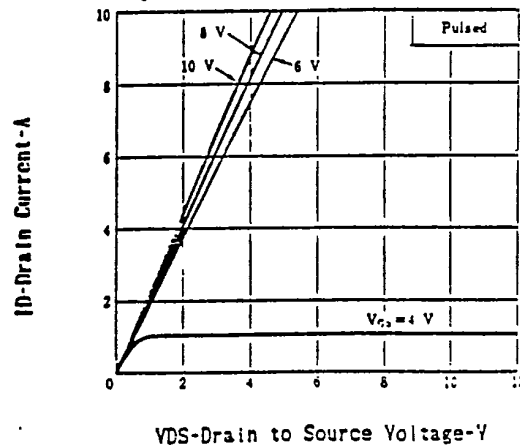
FORWARD BIAS SAFE OPERATING AREA

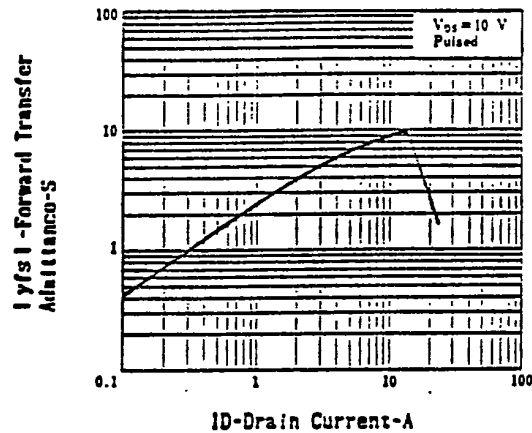
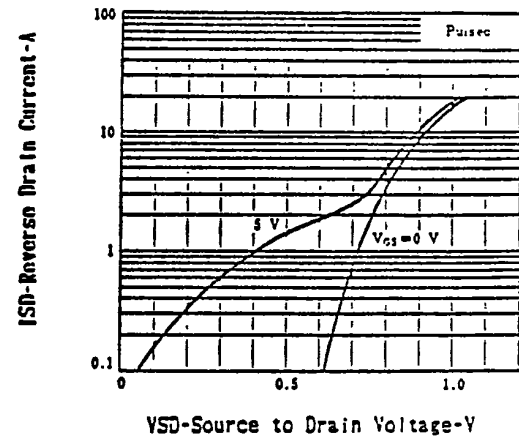
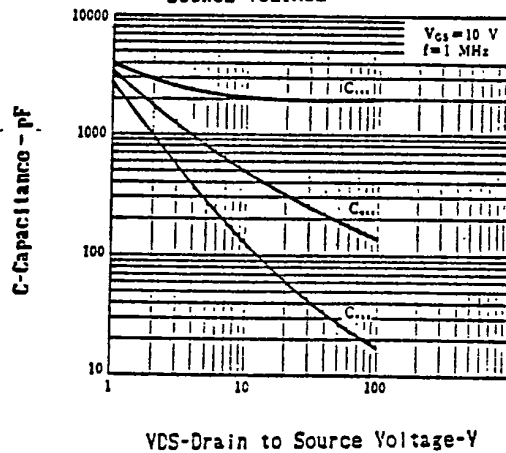
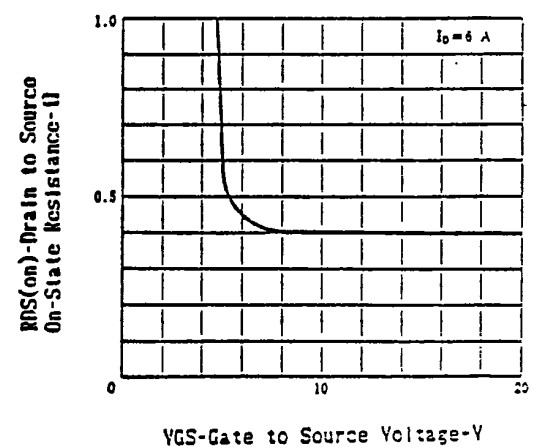
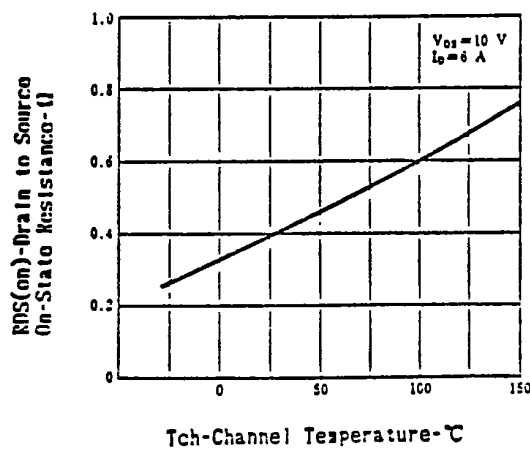
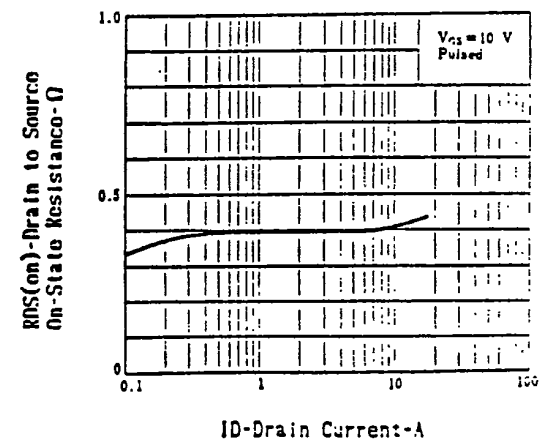


TOTAL POWER DISSIPATION vs. CASE TEMPERATURE



DRAIN CURRENT vs. DRAIN TO SOURCE VOLTAGE



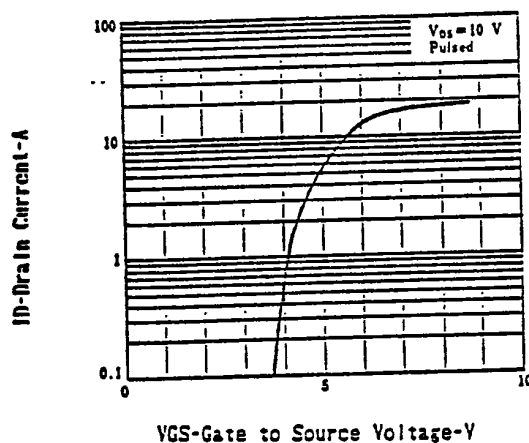
FORWARD TRANSFER ADMITTANCE
vs. DRAIN CURRENTSOURCE TO DRAIN DIODE
FORWARD VOLTAGECAPACITANCE vs. DRAIN TO
SOURCE VOLTAGEDRAIN TO SOURCE ON-STATE RESISTANCE
vs. GATE TO SOURCE VOLTAGEDRAIN TO SOURCE ON-STATE RESISTANCE
vs. CHANNEL TEMPERATUREDRAIN TO SOURCE ON-STATE RESISTANCE
vs. DRAIN CURRENT

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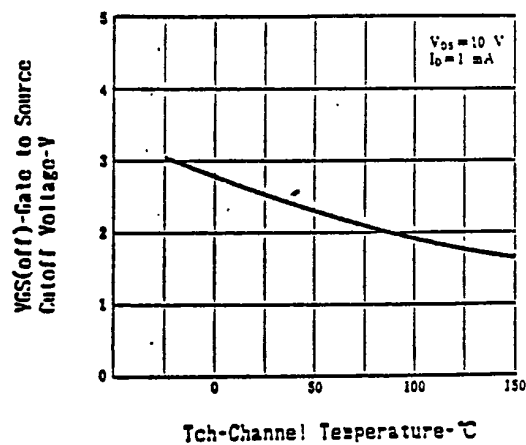
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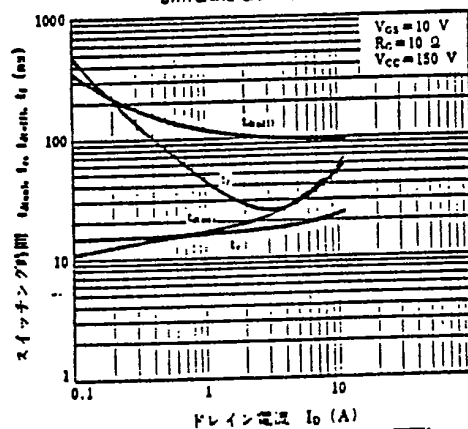
TRANSFER CHARACTERISTICS



GATE TO SOURCE CUTOFF VOLTAGE vs. CHANNEL TEMPERATURE



SWITCHING CHARACTERISTICS



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